

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1460bin8-5#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 0.497971**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001361	1000000	2733.08935547		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000076	1000000	152.619232178		
Lead Frame	A42	Copper (Cu)	7440-50-8	0.000000	0	0		
		Iron (Fe)	7439-89-6	0.089088	580000	178901.875		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.064512	420000	129549.640625		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.153600</b>	<b>1000000</b>	<b>308451.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.012410	1000000	24921.6992188		
		<b>External Plating Total:</b>				<b>0.012410</b>	<b>1000000</b>	<b>24921.6992188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001228	1000000	2466.00585938		
<b>Internal Plating Total:</b>				<b>0.001228</b>	<b>1000000</b>	<b>2466.00585938</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000540	750000	1084.39978027		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000180	250000	361.466644287		
<b>Die Attach Total:</b>				<b>0.000720</b>	<b>1000000</b>	<b>1445.86657715</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.044319	135000	88999.109375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.282330	860000	566960.375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.001641	5000	3295.37084961		
		<b>Encapsulation Total:</b>				<b>0.328290</b>	<b>1000000</b>	<b>659254.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000286	1000000	574.33026123		
					<b>TOTAL MASS (g) :</b>	<b>0.497971</b>		